

QuikLaze™-50ST/STR

Micro-Electronics Trimming and Repair System



Applications

Providing quick and easy removal of a variety of materials from microelectronic devices.

- LCD repair: Remove ITO shorts – cut metal lines
- Resistor trimming: Trim small batches of thick- and thin-film resistors
- Capacitor trimming: Trim small lots of gold capacitors on ceramic substrates
- Kapton removal: Remove a section of kapton from flex circuits
- Polyimide removal: Remove polyamide from semiconductor devices prior to FIB edits

Features

- Compact laser-head design with stepper motor for high repeatability and precise cutting
- Uniform cuts from 50 x 50µm (with 50X objective) to 1 x 1µm (with 100X objective)
- Optional rotational aperture for 0±45° cuts at 1° increment
- User-selectable wavelengths (1064nm, 532nm, 355nm, and/or 266nm) for cutting and machining a wide range of materials
- Simplified operation via intuitive micro-processor-based, remote-control panel, or through an RS232 interface
- Single-shot or continuous trigger at a variable repetition rate for excellent control during material removal
- Versatile operating software that allows precise control of machining
- Easy to install and operate

U.S. Patent Nos. 5,611,946, 5,811,751, 5,963,264, 5,703,713

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from Micromanipulator**

